AMENDMENTS TO THE SPECIFICATION

[0021] Coupled at its base (base 110) to transceiver board 305 and fiber submount 340 is subassembly 100. In this embodiment, subassembly 100 is disposed between transceiver board 305 and fiber submount 340, such that an opening (or openings) in base 110 of subassembly 100 overly the opening between transceiver board 305 and fiber submount 340. Specifically, opening 160 overlies an emission path from VCSEL 325 allowing a light emission into subassembly 100. It is appreciated, although not shown in this illustration, that a second opening (disposed along a Z axis into the plane of the page) is similarly situated to allow VCSEL submount 320 to receive signals (e.g., receive signals at photodetector 328) to complete a data link.

[0023] In the embodiment shown in **Figure 2**, subassembly 100 is designed to ~~compliment~~ complement a state-of-the-art formfactor for transceiver boards. Specifically, a state-of-the-art transceiver assembly (transceiver assembly 300) has a length in the X-direction on the order of 30 to 50 millimeters (denoted by reference numeral 365). The transceiver assembly has a height on the order of 8 to 10 millimeters (denoted by reference numeral 370). Given these constraints, it is also desired for high speed data transmissions that the distance between an emitter surface, such as a surface of VCSEL subassembly, and fiber core 210 is on the order of 3 to 4 millimeters (e.g., 3.4 millimeters). Subassembly 100 accommodates the formfactor limitations through the use of angled second side wall 130 having reflective component 140. In this manner, subassembly 100 redirects (in the orientation shown) a vertical (Y-direction) light emission to a lateral light emission or vice versa through angled second side wall 130.